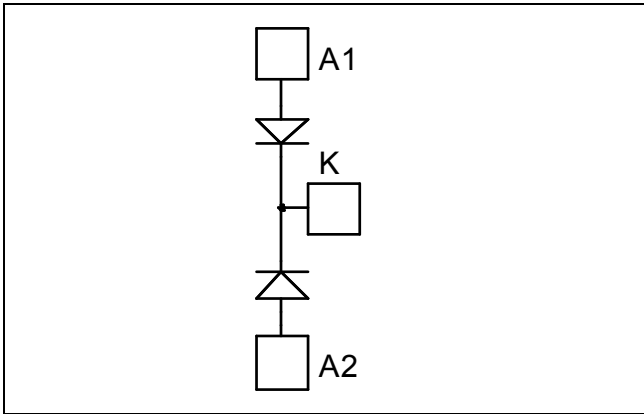


## Dual Common Cathode diodes Power Module

**$V_{RRM} = 1000V$**   
 **$I_C = 400A @ T_c = 70^\circ C$**



### Application

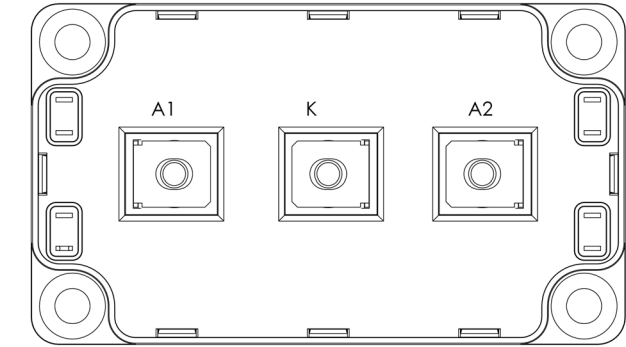
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant



### Absolute maximum ratings

| Symbol       | Parameter                               | Max ratings        | Unit |
|--------------|---|--------------------|------|
| $V_R$        | Maximum DC reverse Voltage              | 1000               | V    |
| $V_{RRM}$    | Maximum Peak Repetitive Reverse Voltage |                    |      |
| $I_{F(AV)}$  | Maximum Average Forward Current         | Duty cycle = 50%   | A    |
|              |   | $T_C = 25^\circ C$ |      |
|              |   | $T_C = 70^\circ C$ | 400  |
| $I_{F(RMS)}$ | RMS Forward Current                     | Duty cycle = 50%   | 500  |
| $I_{FSM}$    | Non-Repetitive Forward Surge Current    | 8.3ms              | 3000 |
|              |   | $T_C = 45^\circ C$ |      |

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

| Symbol   | Characteristic                  | Test Conditions      | Min                       | Typ | Max  | Unit          |
|----------|---------------------------------|----------------------|---------------------------|-----|------|---------------|
| $V_F$    | Diode Forward Voltage           | $I_F = 400\text{A}$  |                           | 2.1 | 2.7  | V             |
|          |                                 | $I_F = 600\text{A}$  |                           | 2.3 |      |               |
|          |                                 | $I_F = 400\text{A}$  | $T_j = 125^\circ\text{C}$ | 1.7 |      |               |
| $I_{RM}$ | Maximum Reverse Leakage Current | $V_R = 1000\text{V}$ | $T_j = 25^\circ\text{C}$  |     | 250  | $\mu\text{A}$ |
|          |                                 |                      | $T_j = 125^\circ\text{C}$ |     | 1000 |               |
| $C_T$    | Junction Capacitance            | $V_R = 1000\text{V}$ |                           | 480 |      | pF            |

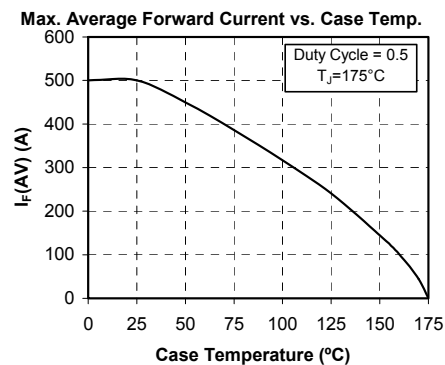
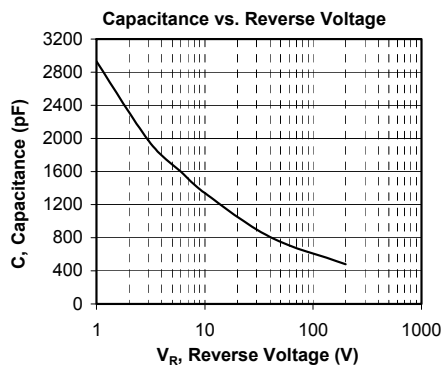
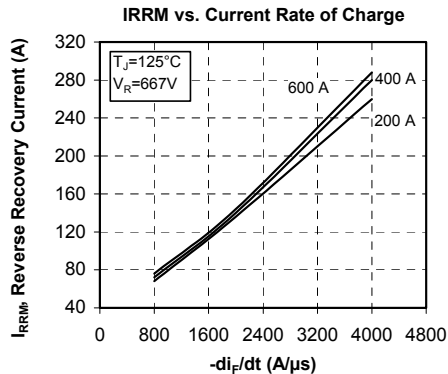
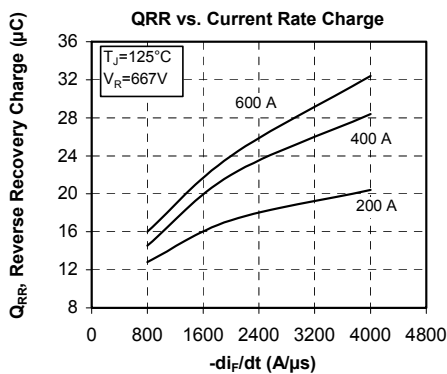
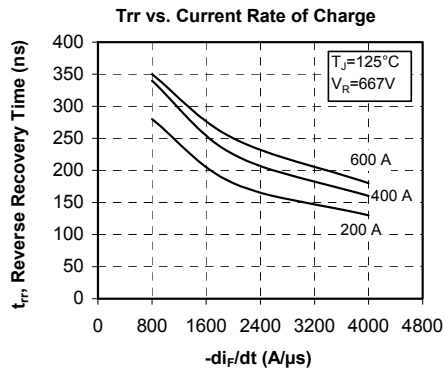
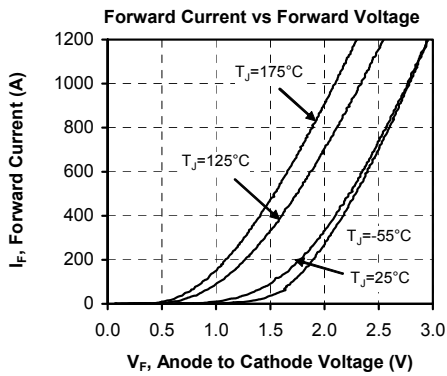
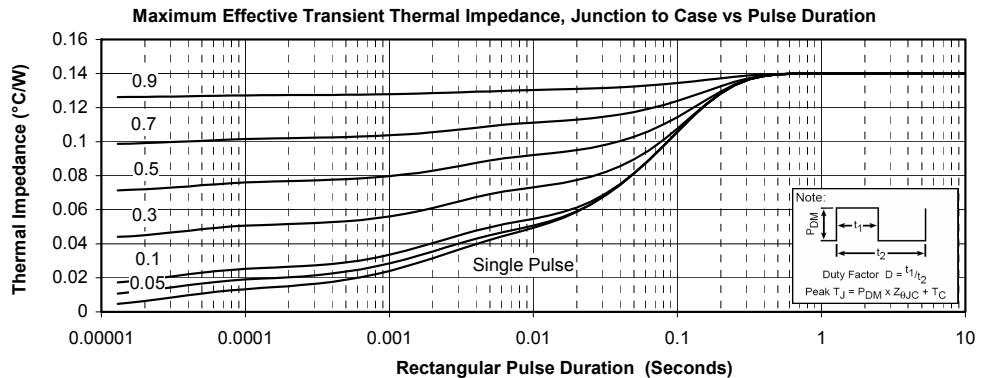
**Dynamic Characteristics**

| Symbol    | Characteristic           | Test Conditions  | Min                       | Typ  | Max | Unit          |
|-----------|--------------------------|--|---------------------------|------|-----|---------------|
| $t_{rr}$  | Reverse Recovery Time    | $I_F = 1\text{A}, V_R = 30\text{V}$<br>$di/dt = 400\text{A}/\mu\text{s}$         | $T_j = 25^\circ\text{C}$  | 45   |     | ns            |
| $t_{rr}$  | Reverse Recovery Time    |  | $T_j = 25^\circ\text{C}$  | 290  |     | ns            |
|           |                          |  | $T_j = 125^\circ\text{C}$ | 340  |     |               |
| $Q_{rr}$  | Reverse Recovery Charge  | $I_F = 400\text{A}$<br>$V_R = 667\text{V}$<br>$di/dt = 800\text{A}/\mu\text{s}$  | $T_j = 25^\circ\text{C}$  | 2.7  |     | $\mu\text{C}$ |
|           |                          |  | $T_j = 125^\circ\text{C}$ | 14.6 |     |               |
| $I_{RRM}$ | Reverse Recovery Current |  | $T_j = 25^\circ\text{C}$  | 24   |     | A             |
|           |                          |  | $T_j = 125^\circ\text{C}$ | 72   |     |               |
| $t_{rr}$  | Reverse Recovery Time    | $I_F = 400\text{A}$<br>$V_R = 667\text{V}$<br>$di/dt = 4000\text{A}/\mu\text{s}$ | $T_j = 125^\circ\text{C}$ | 160  |     | ns            |
| $Q_{rr}$  | Reverse Recovery Charge  |  |                           | 28.4 |     | $\mu\text{C}$ |
| $I_{RRM}$ | Reverse Recovery Current |  |                           | 280  |     | A             |

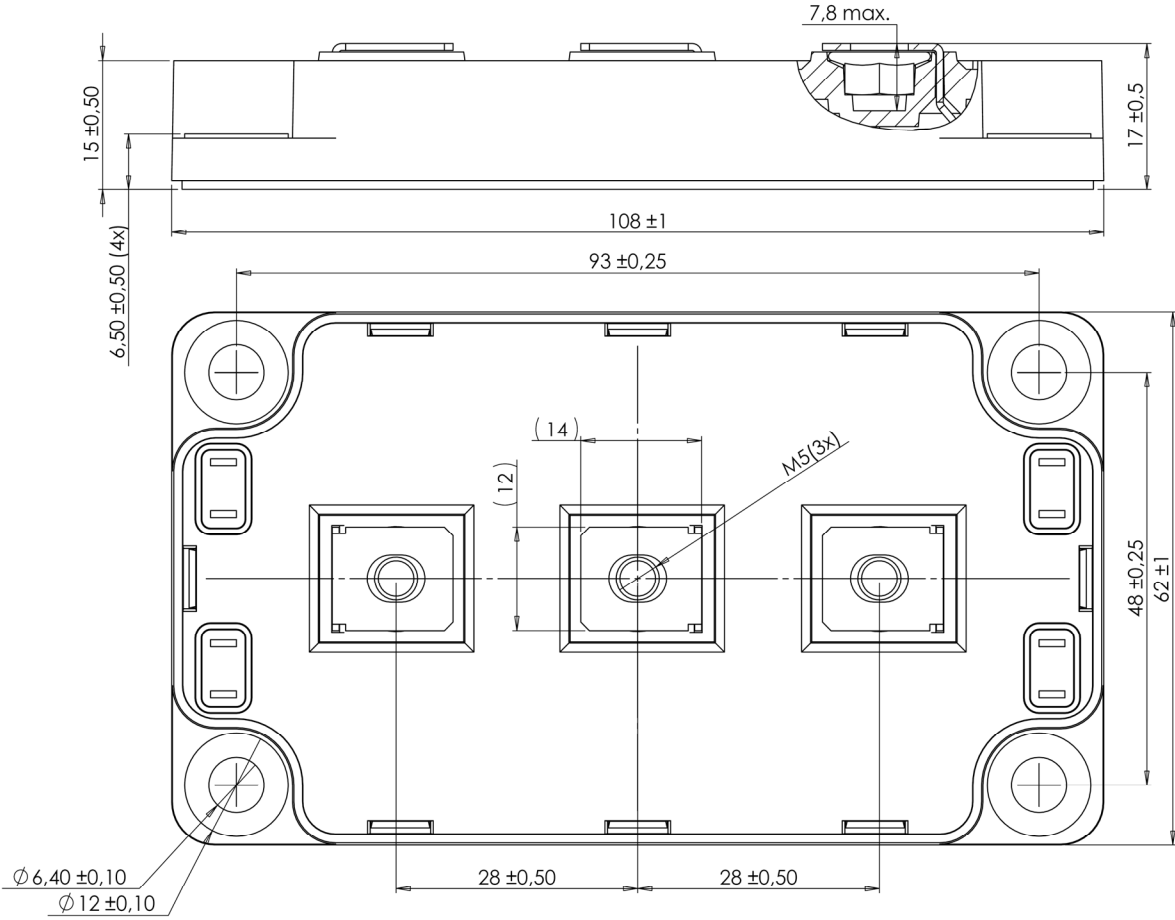
**Thermal and package characteristics**

| Symbol     | Characteristic   | Min           | Typ | Max  | Unit                      |     |
|------------|--|---------------|-----|------|---------------------------|-----|
| $R_{thJC}$ | Junction to Case   |               |     | 0.14 | $^\circ\text{C}/\text{W}$ |     |
| $V_{ISOL}$ | RMS Isolation Voltage, any terminal to case $t = 1\text{ min}, 50/60\text{Hz}$ | 4000          |     |      | V                         |     |
| $T_j$      | Operating junction temperature range   | -40           |     | 175  | $^\circ\text{C}$          |     |
| $T_{STG}$  | Storage Temperature Range  | -40           |     | 125  |                           |     |
| $T_C$      | Operating Case Temperature   | -40           |     | 100  |                           |     |
| Torque     | Mounting torque  | To heatsink   | M6  | 3    | 5                         | N.m |
|            |  | For terminals | M5  | 2    | 3.5                       |     |
| Wt         | Package Weight   |               |     | 300  | g                         |     |

## Typical Performance Curve



**SP6 Package outline** (dimensions in mm)



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